

Applicant : Detlef Weber
Serial No. : Not assigned yet
Filed : Herewith
Title : METALLIZATION ARRANGEMENT FOR SEMICONDUCTOR STRUCTURE
AND CORRESPONDING FABRICATION METHOD

PRELIMINARY AMENDMENT

In the specification:

- On page 1, line 1, delete "Description"
- On page 1, line 5, insert - BACKGROUND--
- On page 2, line 24, insert --SUMMARY--
- On page 2, delete the paragraph that begins on line 28.
- On page 3, line 6, delete the paragraph beginning on line 6.
- On page 4, line 18, insert BRIEF DESCRIPTION OF THE FIGURES--
- On page 4, line 31, insert --DETAILED DESCRIPTION--

Please cancel claims 1-6 and claims 7-13.

Please consider the following new claims 14-20 and 21-27.

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I hereby certify under 37 CFR §1.10 that this correspondence is being deposited with the United States Postal Service as Express Mail Post Office to Addressee with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

July 3, 2001

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